

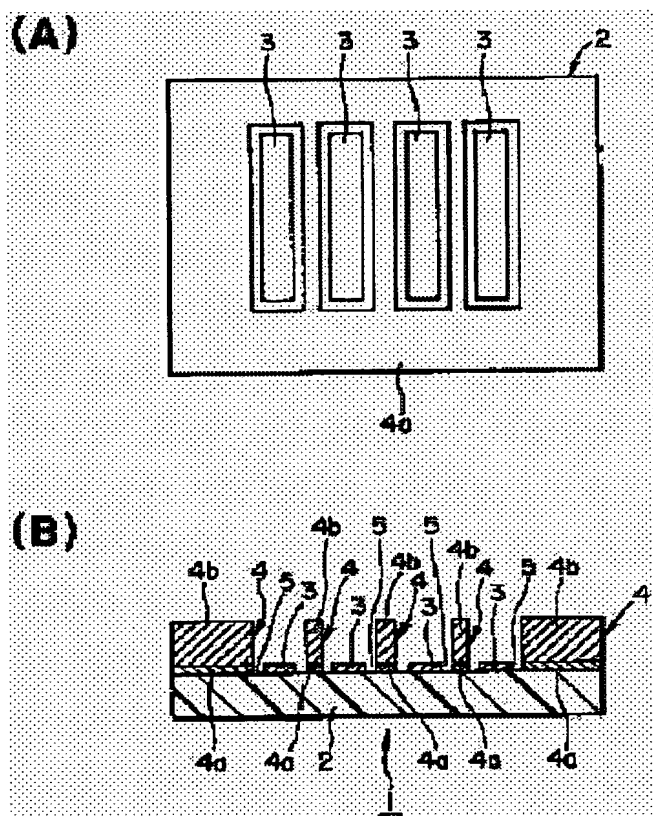
PRINTED CIRCUIT BOARD

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Abstract of JP10112580

PROBLEM TO BE SOLVED: To form each barrier made of solder resists between the respective adjacent electrode lands of a printed circuit board of an electronic part by superimposing in the form of two layers a photosensitive dry-film-form solder resist on an ordinary liquid resist provided on its main body of the board, in order to prevent solder-bridge faults generated between SMD electrodes, such as the ones of a flat package IC with terminal pitch not larger than about 0.65mm and generated between parts, in the soldering processes of the electronic part.

SOLUTION: Forming each thin film made of a photosensitive liquid solder resist 4a of one of either an alkali developing type or a water soluble type on the single surface of a board main body 2 of a printed circuit board 1 by printing, exposing and developing, a photosensitive dry-film-form solder resist 4b of either one of an alkali developing type or water soluble type is stuck further thereon to form each of the thick films made of the resist 4b by exposing and developing. Thereby, each two-layer structure barrier 4 made of the solder resists 4a, 4b is formed progressively in the position surrounding each copper foil electrode 3 on the board main body 2.



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